



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D *: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	15-01-2018
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	MDG MD CHAMPION	Representative Title	MDG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		


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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
M95256-DFMC6TG	CGZW*9556BKB	A	P1C7	15-01-2018
	Amount	UoM	Unit type	ST ECOPACK Grade
	16.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	2x3x0.6	8	No lead	
Comment	Package : ZW UDFPN 2x3x0.6 8L 0.5MM PITCH 7558452			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	CGZW*95568KB				4999995.0	1000005.0
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	0.896	mg	supplier	die	Silicon (Si)	7440-21-3		0.849	mg	947545	53063
				supplier	metallization	Aluminium (Al)	7429-90-5		0.004	mg	4464	250
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	1116	63
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	1116	63
				supplier	Passivation	Silicon Nitride	12033-89-5		0.003	mg	3348	188
				supplier	Passivation	Silicon Oxide	7631-86-9		0.038	mg	42411	2375
Lead-frame	M-011 Other inorganic materials	3.006	mg	supplier	alloy	Copper (Cu)	7440-50-8		2.917	mg	970218	182294
				supplier	alloy	Iron (Fe)	7439-89-6		0.070	mg	23362	4390
				supplier	alloy	Zinc (Zn)	7440-66-6		0.004	mg	1195	225
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.003	mg	836	157
				supplier	coating	Nickel (Ni)	7440-02-0		0.012	mg	4020	755
				supplier	coating	Palladium (Pd)	7440-05-3		0.001	mg	257	48
				supplier	coating	Gold (Au)	7440-57-5		0.000	mg	107	20
				supplier	coating							
Die Attach	M-011 Other inorganic materials	1.266	mg	supplier	glue or soft solder	Silver (Ag)	7440-22-4		1.108	mg	875000	69248
				supplier	glue or soft solder	polymer	28630-26-4		0.101	mg	80000	6331
				supplier	glue or soft solder	aniline	67784-74-1		0.013	mg	10000	791
				supplier	glue or soft solder	epoxy resin	Proprietary		0.038	mg	30000	2374
				supplier	glue or soft solder	Epoxy resin molecular weight <= 700	Proprietary		0.006	mg	5000	396
Wires	M-011 Other inorganic materials	0.036	mg	supplier	Bonding wire	Gold (Au)	7440-57-5		0.036	mg	1000000	2258
Encapsulation	M-011 Other inorganic materials	10.795	mg	supplier	Moulding Compound	silica vitreous	60676-86-0		9.252	mg	856982	578219
				supplier	Moulding Compound	Phenol resin	9003-35-4		0.368	mg	34052	22975
				supplier	Moulding Compound	epoxy resin	Proprietary		0.420	mg	38916	26258
				supplier	Moulding Compound	carbon black	1333-86-4		0.021	mg	1946	1313
				supplier	Moulding Compound	Biphenyl epoxy resin	85954-11-6		0.210	mg	19458	13129
				supplier	Moulding Compound	Magnesium hydroxide	1309-42-8		0.525	mg	48646	32822